

74LVC02A

Quad 2-input NOR gate

Rev. 8 — 16 November 2011

Product data sheet

1. General description

The 74LVC02A provides four 2-input NOR gates.

Inputs can be driven from either 3.3 V or 5 V devices. This feature allows the use of these devices as translators in mixed 3.3 V and 5 V applications.

2. Features and benefits

- 5 V tolerant inputs for interfacing with 5 V logic
- Wide supply voltage range from 1.2 V to 3.6 V
- CMOS low power consumption
- Direct interface with TTL levels
- Complies with JEDEC standard:
 - ◆ JESD8-7A (1.65 V to 1.95 V)
 - ◆ JESD8-5A (2.3 V to 2.7 V)
 - ◆ JESD8-C/JESD36 (2.7 V to 3.6 V)
- ESD protection:
 - ◆ HBM JESD22-A114F exceeds 2000 V
 - ◆ MM JESD22-A115-B exceeds 200 V
 - ◆ CDM JESD22-C101E exceeds 1000 V
- Specified from $-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$ and $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$

3. Ordering information

Table 1. Ordering information

Type number	Package			Version
	Temperature range	Name	Description	
74LVC02AD	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	SO14	plastic small outline package; 14 leads; body width 3.9 mm	SOT108-1
74LVC02ADB	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	SSOP14	plastic shrink small outline package; 14 leads; body width 5.3 mm	SOT337-1
74LVC02APW	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	TSSOP14	plastic thin shrink small outline package; 14 leads; body width 4.4 mm	SOT402-1
74LVC02ABQ	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	DHVQFN14	plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body $2.5 \times 3 \times 0.85\text{ mm}$	SOT762-1



4. Functional diagram

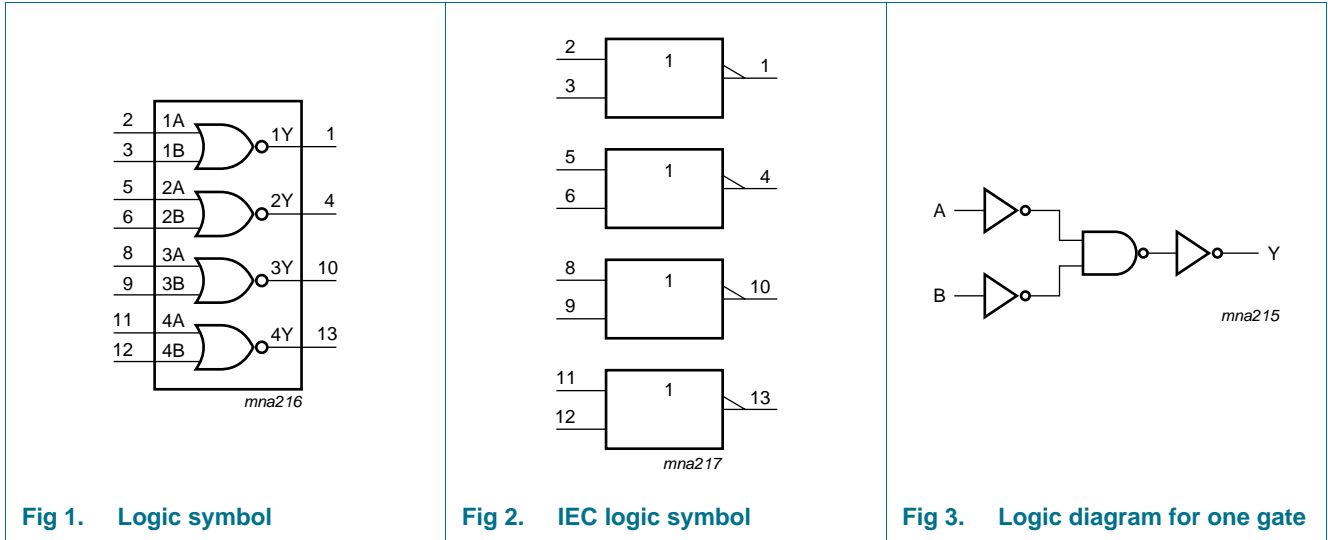


Fig 1. Logic symbol

Fig 2. IEC logic symbol

Fig 3. Logic diagram for one gate

5. Pinning information

5.1 Pinning

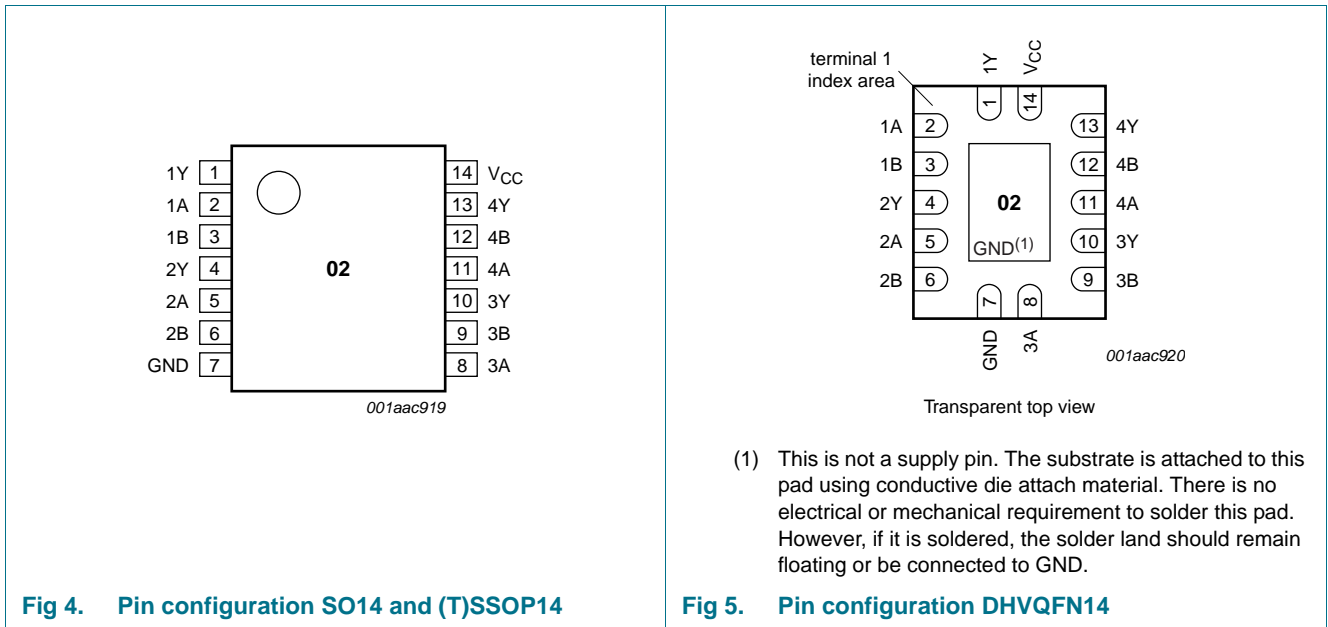


Fig 4. Pin configuration SO14 and (T)SSOP14

Fig 5. Pin configuration DHVQFN14

(1) This is not a supply pin. The substrate is attached to this pad using conductive die attach material. There is no electrical or mechanical requirement to solder this pad. However, if it is soldered, the solder land should remain floating or be connected to GND.

5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
1Y to 4Y	1, 4, 10, 13	data output
1A to 4A	2, 5, 8, 11	data input
1B to 4B	3, 6, 9, 12	data input
GND	7	ground (0 V)
V _{CC}	14	supply voltage

6. Functional description

Table 3. Function table^[1]

Input nA	Input nB	Output nY
L	L	H
X	H	L
H	X	L

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	supply voltage		-0.5	+6.5	V
I _{IK}	input clamping current	V _I < 0 V	-50	-	mA
V _I	input voltage		^[1] -0.5	+6.5	V
I _{OK}	output clamping current	V _O > V _{CC} or V _O < 0 V	-	±50	mA
V _O	output voltage	output in HIGH or LOW-state	^[2] -0.5	V _{CC} + 0.5	V
I _O	output current	V _O = 0 V to V _{CC}	-	±50	mA
I _{CC}	supply current		-	100	mA
I _{GND}	ground current		-100	-	mA
P _{tot}	total power dissipation	T _{amb} = -40 °C to +125 °C	^[3] -	500	mW
T _{stg}	storage temperature		-65	+150	°C

[1] The minimum input voltage ratings may be exceeded if the input current ratings are observed.

[2] The output voltage ratings may be exceeded if the output current ratings are observed.

[3] For SO14 packages: above 70 °C derate linearly with 8 mW/K.

For (T)SSOP14 packages: above 60 °C derate linearly with 5.5 mW/K.

For DHVQFN14 packages: above 60 °C derate linearly with 4.5 mW/K.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CC}	supply voltage		1.65	-	3.6	V
		functional	1.2	-	-	V
V_I	input voltage		0	-	5.5	V
V_O	output voltage	output HIGH or LOW state	0	-	V_{CC}	V
T_{amb}	ambient temperature		-40	-	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 1.65 \text{ V to } 2.7 \text{ V}$	0	-	20	ns/V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	0	-	10	ns/V

9. Static characteristics

Table 6. Static characteristics

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ ^[1]	Max	Min	Max	
V_{IH}	HIGH-level input voltage	$V_{CC} = 1.2 \text{ V}$	1.08	-	-	1.08	-	V
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	$0.65 \times V_{CC}$	-	-	$0.65 \times V_{CC}$	-	V
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7	-	-	1.7	-	V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2.0	-	-	2.0	-	V
V_{IL}	LOW-level input voltage	$V_{CC} = 1.2 \text{ V}$	-	-	0.12	-	0.12	V
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	-	-	$0.35 \times V_{CC}$	-	$0.35 \times V_{CC}$	V
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	-	-	0.7	-	0.7	V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	-	-	0.8	-	0.8	V
V_{OH}	HIGH-level output voltage	$V_I = V_{IH} \text{ or } V_{IL}$						
		$I_O = -100 \mu\text{A}; V_{CC} = 1.65 \text{ V to } 3.6 \text{ V}$	$V_{CC} - 0.2$	-	-	$V_{CC} - 0.3$	-	V
		$I_O = -4 \text{ mA}; V_{CC} = 1.65 \text{ V}$	1.2	-	-	1.05	-	V
		$I_O = -8 \text{ mA}; V_{CC} = 2.3 \text{ V}$	1.8	-	-	1.65	-	V
		$I_O = -12 \text{ mA}; V_{CC} = 2.7 \text{ V}$	2.2	-	-	2.05	-	V
		$I_O = -18 \text{ mA}; V_{CC} = 3.0 \text{ V}$	2.4	-	-	2.25	-	V
V_{OL}	LOW-level output voltage	$V_I = V_{IH} \text{ or } V_{IL}$						
		$I_O = 100 \mu\text{A}; V_{CC} = 1.65 \text{ V to } 3.6 \text{ V}$	-	-	0.2	-	0.3	V
		$I_O = 4 \text{ mA}; V_{CC} = 1.65 \text{ V}$	-	-	0.45	-	0.65	V
		$I_O = 8 \text{ mA}; V_{CC} = 2.3 \text{ V}$	-	-	0.6	-	0.8	V
		$I_O = 12 \text{ mA}; V_{CC} = 2.7 \text{ V}$	-	-	0.4	-	0.6	V
		$I_O = 24 \text{ mA}; V_{CC} = 3.0 \text{ V}$	-	-	0.55	-	0.8	V
I_I	input leakage current	$V_{CC} = 3.6 \text{ V}; V_I = 5.5 \text{ V or GND}$	-	± 0.1	± 5	-	± 20	μA

Table 6. Static characteristics ...continued

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ ^[1]	Max	Min	Max	
I _{CC}	supply current	V _{CC} = 3.6 V; V _I = V _{CC} or GND; I _O = 0 A	-	0.1	10	-	40	μA
ΔI _{CC}	additional supply current	per input pin; V _{CC} = 2.7 V to 3.6 V; V _I = V _{CC} - 0.6 V; I _O = 0 A	-	5	500	-	5000	μA
C _I	input capacitance	V _{CC} = 0 V to 3.6 V; V _I = GND to V _{CC}	-	4.0	-	-	-	pF

[1] All typical values are measured at V_{CC} = 3.3 V (unless stated otherwise) and T_{amb} = 25 °C.

10. Dynamic characteristics

Table 7. Dynamic characteristicsVoltages are referenced to GND (ground = 0 V). For test circuit see [Figure 7](#).

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ ^[1]	Max	Min	Max	
t _{pd}	propagation delay	nA, nB to nY; see Figure 6 ^[2]						
		V _{CC} = 1.2 V	-	14	-	-	-	ns
		V _{CC} = 1.65 V to 1.95 V	0.5	4.0	8.6	0.5	10.1	ns
		V _{CC} = 2.3 V to 2.7 V	1.0	2.4	4.9	1.0	5.7	ns
		V _{CC} = 2.7 V	1.0	2.5	5.1	1.0	6.5	ns
		V _{CC} = 3.0 V to 3.6 V	1.0	2.2	4.4	1.0	5.5	ns
t _{sk(o)}	output skew time	V _{CC} = 3.0 V to 3.6 V ^[3]	-	-	1.0	-	1.5	ns
C _{PD}	power dissipation capacitance	per gate; V _I = GND to V _{CC} ^[4]						
		V _{CC} = 1.65 V to 1.95 V	-	2.5	-	-	-	pF
		V _{CC} = 2.3 V to 2.7 V	-	5.7	-	-	-	pF
		V _{CC} = 3.0 V to 3.6 V	-	8.5	-	-	-	pF

[1] Typical values are measured at T_{amb} = 25 °C and V_{CC} = 1.2 V, 1.8 V, 2.5 V, 2.7 V, and 3.3 V respectively.[2] t_{pd} is the same as t_{PLH} and t_{PHL}.

[3] Skew between any two outputs of the same package switching in the same direction. This parameter is guaranteed by design.

[4] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum(C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

f_i = input frequency in MHz; f_o = output frequency in MHzC_L = output load capacitance in pFV_{CC} = supply voltage in Volts

N = number of inputs switching

Σ(C_L × V_{CC}² × f_o) = sum of the outputs

11. AC waveforms

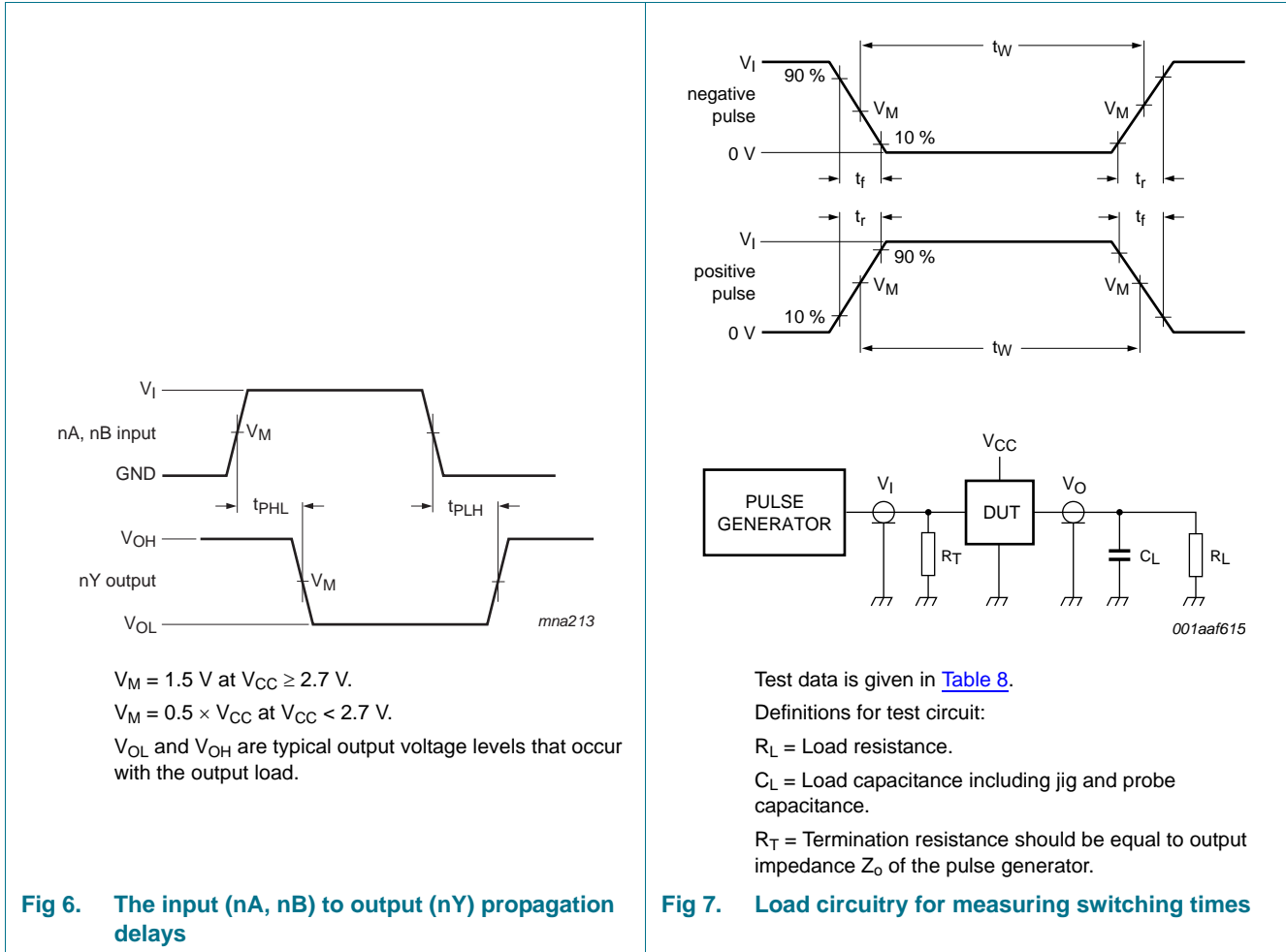


Table 8. Test data

Supply voltage	Input		Load	
	V_I	t_r, t_f	C_L	R_L
1.2 V	V_{CC}	$\leq 2\text{ ns}$	30 pF	1 k Ω
1.65 V to 1.95 V	V_{CC}	$\leq 2\text{ ns}$	30 pF	1 k Ω
2.3 V to 2.7 V	V_{CC}	$\leq 2\text{ ns}$	30 pF	500 Ω
2.7 V	2.7 V	$\leq 2.5\text{ ns}$	50 pF	500 Ω
3.0 V to 3.6 V	2.7 V	$\leq 2.5\text{ ns}$	50 pF	500 Ω

12. Package outline

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1

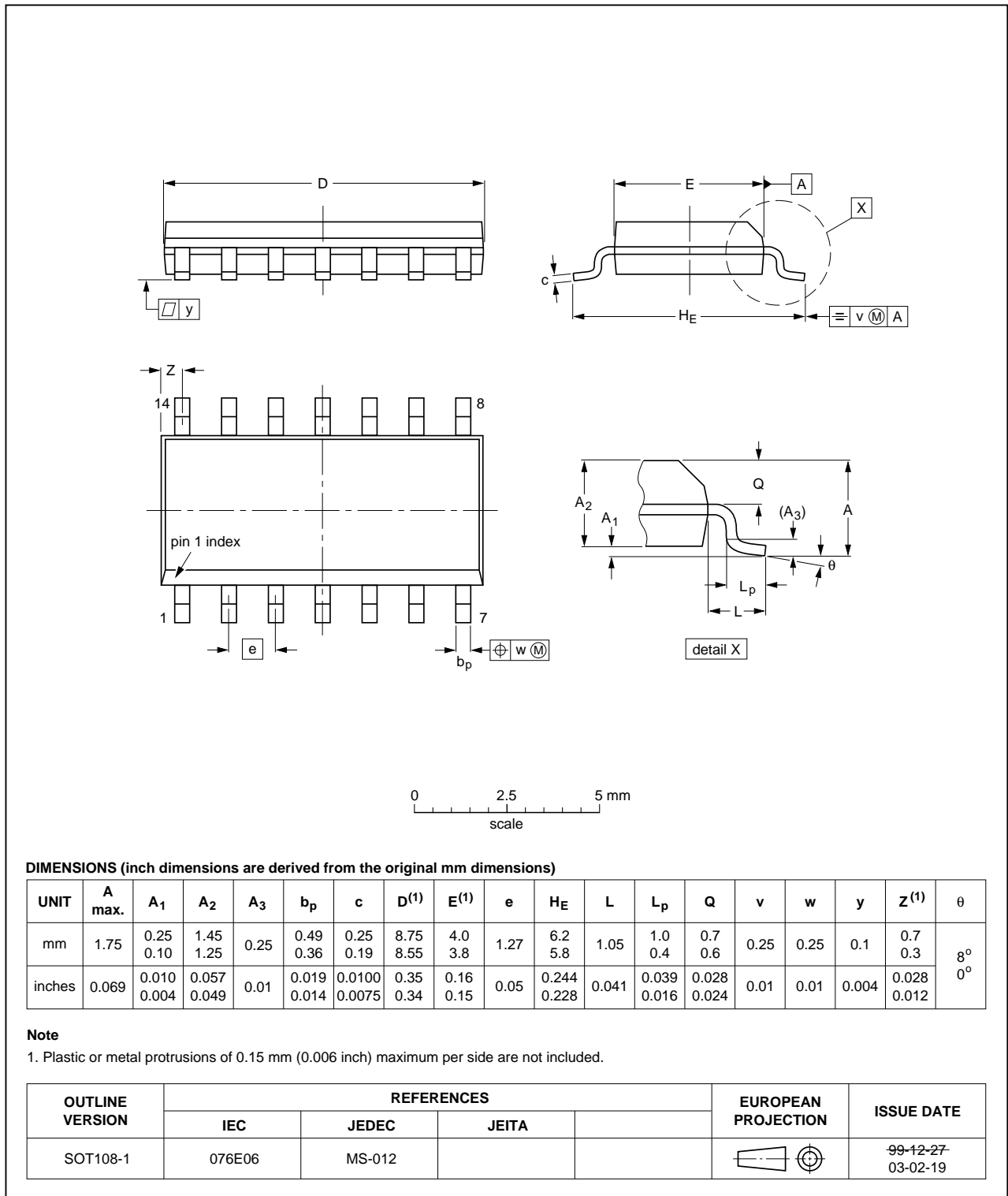


Fig 8. Package outline SOT108-1 (SO14)

SSOP14: plastic shrink small outline package; 14 leads; body width 5.3 mm

SOT337-1

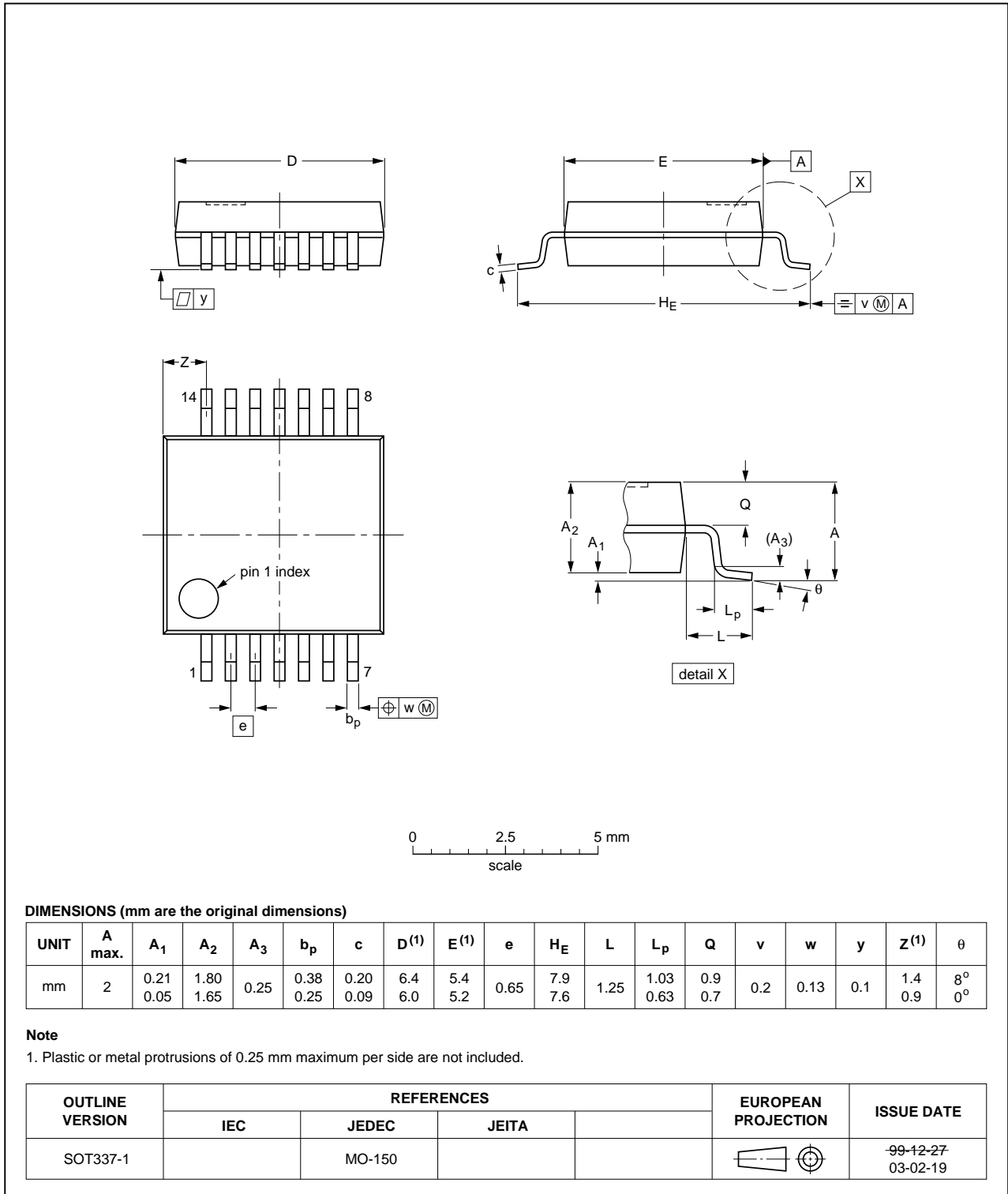


Fig 9. Package outline SOT337-1 (SSOP14)

TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1

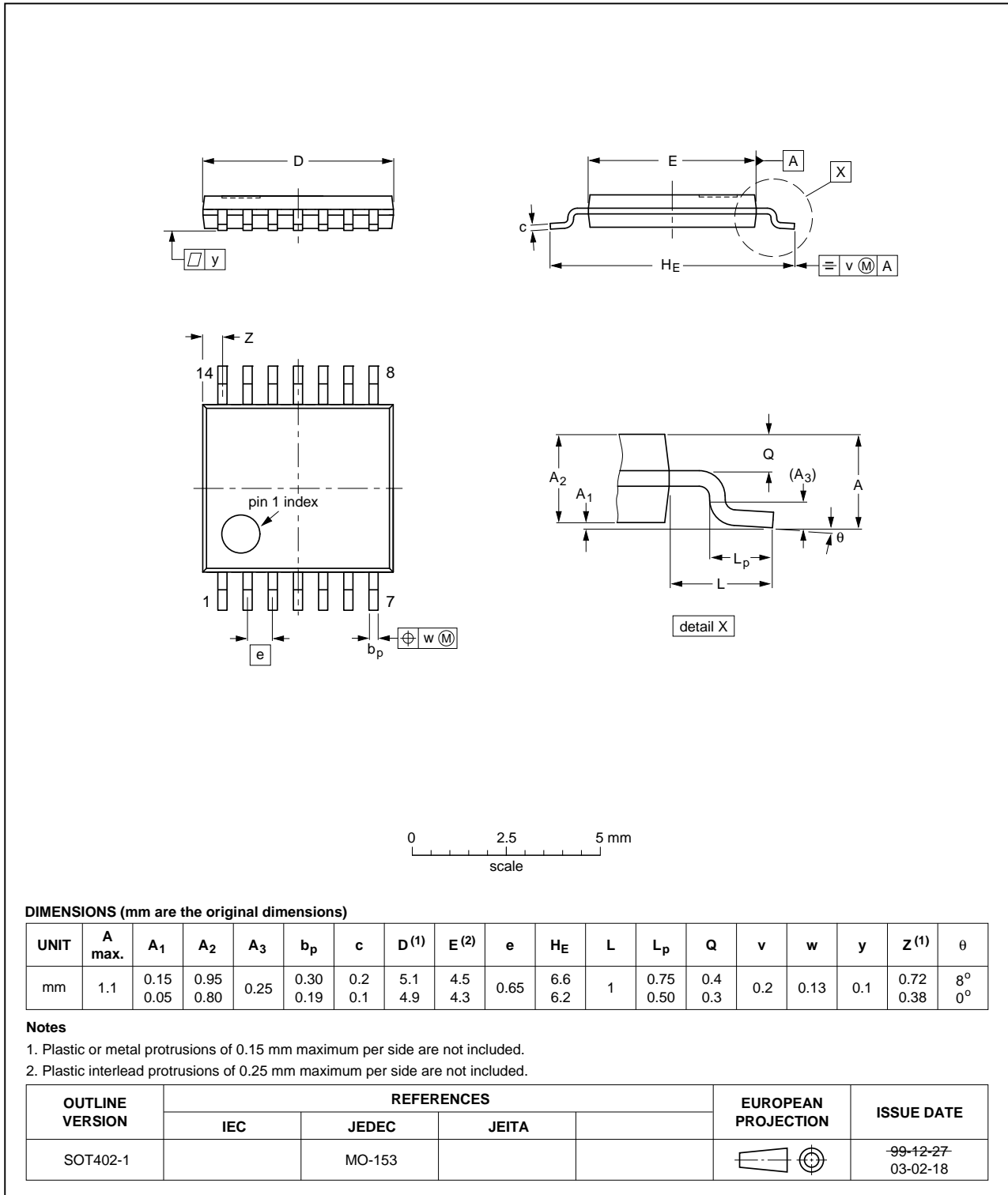


Fig 10. Package outline SOT402-1 (TSSOP14)

DHVQFN14: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 x 3 x 0.85 mm

SOT762-1

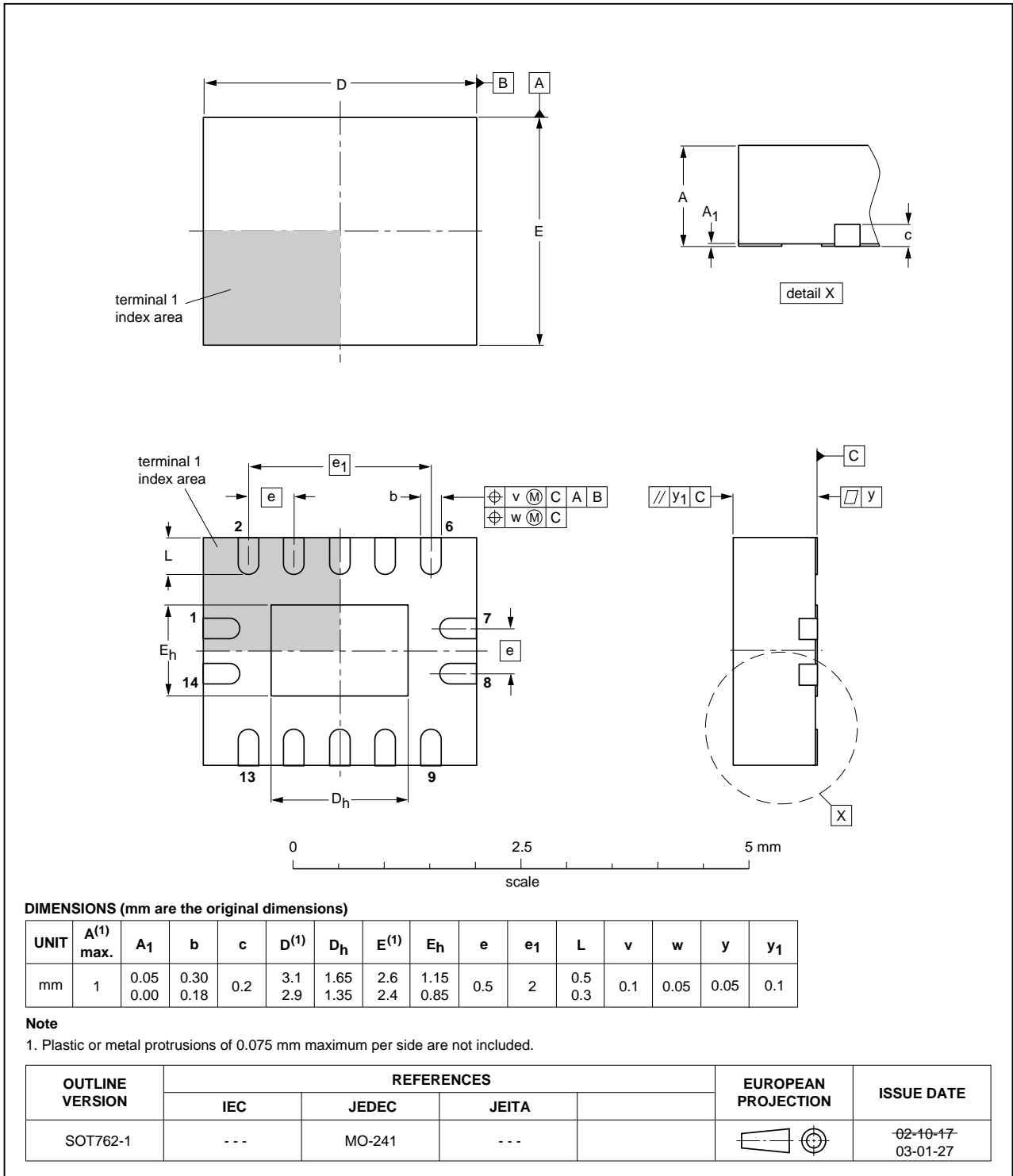


Fig 11. Package outline SOT762-1 (DHVQFN14)

13. Abbreviations

Table 9. Abbreviations

Acronym	Description
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

14. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74LVC02A v.8	20111116	Product data sheet	-	74LVC02A v.7
Modifications:	<ul style="list-style-type: none"> • Legal pages updated. • Table 6, bodyrow ΔI_{CC}: condition V_{CC} changed. 			
74LVC02A v.7	20111019	Product data sheet	-	74LVC02A v.6
74LVC02A v.6	20110809	Product data sheet	-	74LVC02A v.5
74LVC02A v.5	20040312	Product specification	-	74LVC02A v.4
74LVC02A v.4	20030501	Product specification	-	74LVC02A v.3
74LVC02A v.3	20020305	Product specification	-	74LVC02A v.2
74LVC02A v.2	19980428	Product specification	-	74LVC02A v.1
74LVC02A v.1	19970811	Product specification	-	-

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15.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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[2] The term 'short data sheet' is explained in section "Definitions".

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